



Surge arrester

Array arrester with 5 terminals

Series/Type: S30B-A90-4
Ordering code: B88069X5323T203
Date: 2018-11-23
Version: 01

Product description

The S30 array has been developed to meet data transmission protection requirements. The innovative design combines four arresters in one. Due to four connected chambers transverse delay time between the terminals is much shorter than delay times of single parts. Besides this there are other advantages like higher pick & place efficiency and PCB space saving for customers by lightning disturbances. For use in high frequency data lines, the series offers ultra low capacitances and shows only marginally signal losses up to high frequencies. The devices are extremely reliable and are able to withstand high surge currents without destruction.

Features

- Very small size
- Short response time
- Short transverse delay time
- High current capability
- Stable performance over service life
- Ultra low capacitance and insertion loss
- High insulation resistance
- Excellent SMD handling
- RoHS-compatible

Applications

- Ethernet, PoE, xDSL
- Cable modem, splitters, line cards
- Wireless antenna protection

Product characteristics

Physical dimensions (length × width × height)	0.60 × 0.18 × 0.11	in
	15.3 × 4.5 × 2.7	mm
Weight	~ 0.8	g
Operating temperature	-40 ... +125	°C
Recommended storage ¹⁾ - temperature - humidity - period	+5 ... +35 45 ... 80 ≤ 2	°C % years
Climatic category (IEC 60068-1)	40/125/21	
Moisture sensitivity level ²⁾	1	
Marking	without	

Notes:

¹⁾ Specified in terms of corrosion against Sn-plating

²⁾ Tests according to JEDEC J-STD-020

Electrical specifications and stress test methods

Nominal DC spark-over voltage ^{3) 4)}	90	V
Tolerance	±30	%
Min.	63	V
Max.	117	V
Impulse spark-over voltage		
at 100 V/μs	- for 99% of measured values - typical values of distribution	< 500 < 400
at 1 kV/μs	- for 99% of measured values - typical values of distribution	< 700 < 650
Service life ^{5) 6)}		
10 operations [5× (+) & 5× (-)]	8/20 μs	3
10 operations [5× (+) & 5× (-)]	5/320 μs ⁷⁾	150
Insulation resistance at 50 V _{DC} ³⁾	> 1	GΩ
Capacitance at 1 MHz ³⁾	< 0.4	pF
Arc voltage at 1 A	~ 8	V
Glow to arc transition current	< 0.2	A
Glow voltage	~ 50	V

³⁾ At delivery AQL 0.65 level II, DIN ISO 2859

⁴⁾ In ionized mode

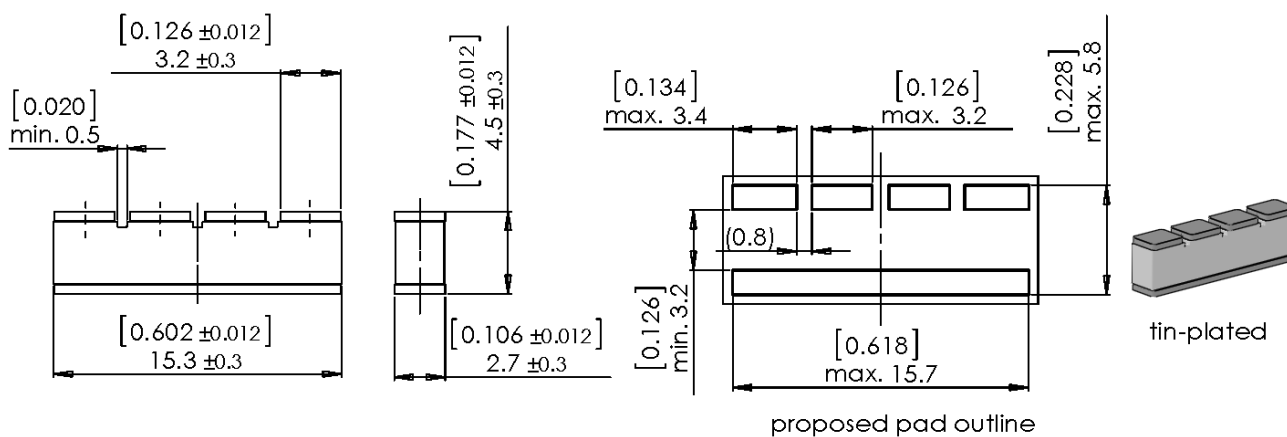
⁵⁾ Terminal 1, 2, 3 or 4 to common terminals 5, see page 4

⁶⁾ Tests according to ITU-T Rec. K. 12 and UL 497B

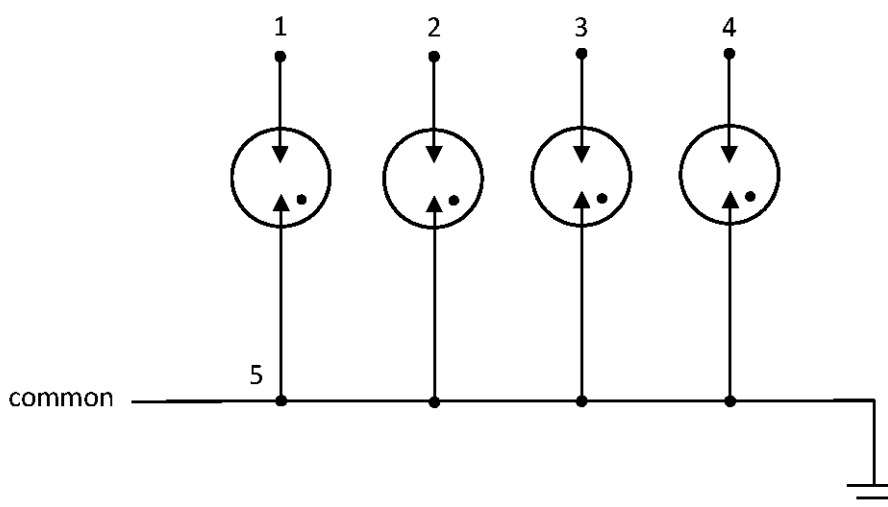
⁷⁾ Test generator 6 kV, 10/700 μs, 40 Ω

Terms and current waveforms in accordance with ITU-T Rec. K. 12; IEC 61643-21 and IEC 61643-311.

Dimensions in mm and inch [...]

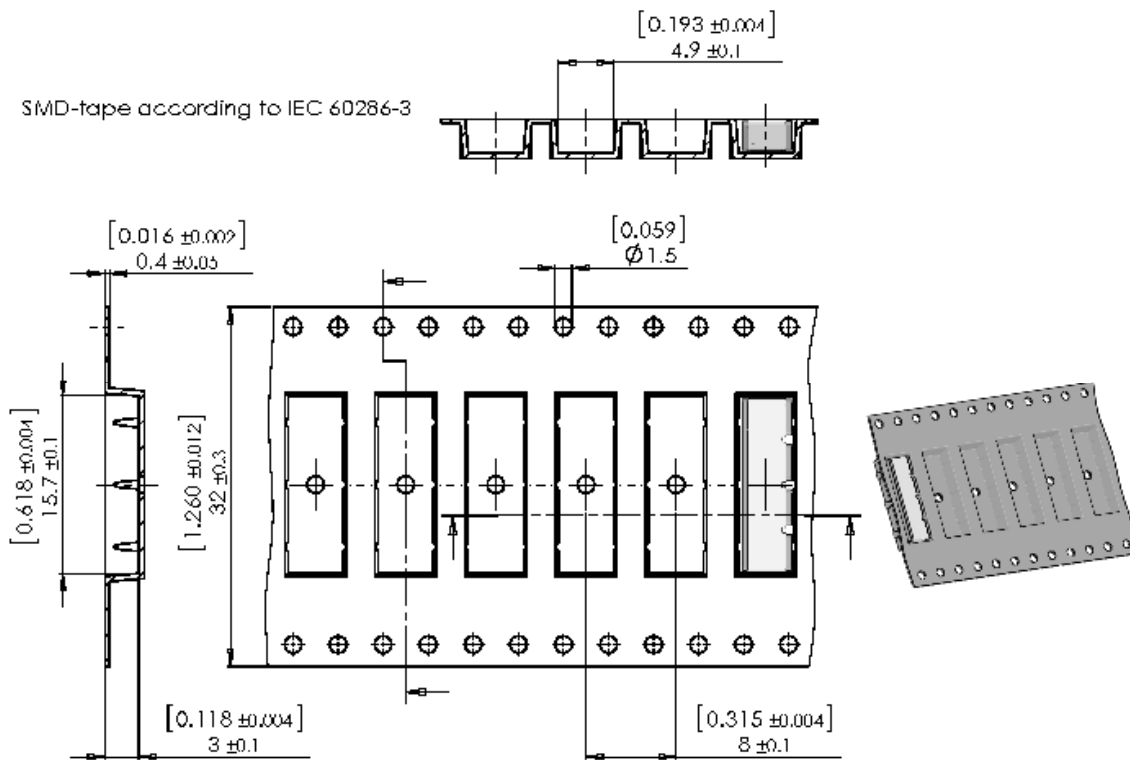


Connection diagram



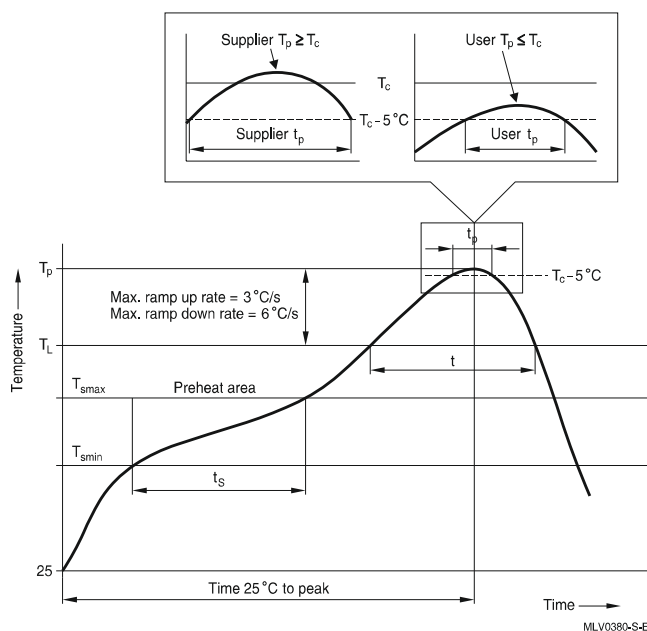
Ordering code and packing advice

B88069X5323T203 = 2000 pcs. on SMD-tape & reel



Soldering parameter

Reflow soldering



Reflow profile features		Sn- Pb eutectic assembly	Pb-free assembly
Preheat and soak - Temperature min - Temperature max - Time	T_{smin} T_{smax} t_{smin} to t_{smax}	100 °C 150 °C 60 ... 120 s	150 °C 200 °C 60 ... 180 s
Average ramp-up rate	T_{smax} to T_p	max. 3 °C/ s	max. 3 °C/ s
Liquidous temperature Time at liquidous	T_L t_L	183 °C 60 ... 150 s	217 °C 60 ... 150 s
Peak package body temperature *, Classification temperature **	T_p , T_c	220 ... 235 °C **	245 ... 260 °C **
Time (t_p) ** within 5 °C of the specified classification temperature (T_c)		20 s ***	30 s ***
Average ramp-down rate	T_p to T_{smax}	max. 6 °C/ s	max. 6 °C/ s
Time 25 °C to peak temperature		max. 6 min	max. 8 min
* = Tolerance for peak profile temperature (T_p) is defined as a supplier minimum and a user maximum. ** = For details please refer to JEDEC J-STD-020D. *** = Tolerance for time at peak profile temperature (t_p) is defined as a supplier minimum and a user maximum.			

Surface mounted components (SMD) may exhibit a temporary increase in the DC spark-over voltage after the solder reflow process. The components will recover within 24 hours. There is no quality defect nor change in protection levels during the temporary change in DC spark-over voltage.

Cautions and warnings

- Do not operate surge arresters in power supply networks, whose maximum operating voltage exceeds the minimum spark-over voltage of the surge arresters.
- Surge arresters may become hot in the event of longer periods of current stress (burn risk). In the event of overload the connectors may fail or the component may be destroyed.
- Surge arresters must be handled with care and must not be dropped.
- Do not continue to use damaged surge arresters.
- The shown SMD pad dimensions represent a safe way to mount the arrester and are a recommendation of the manufacturer. During the reflow process it must be assured that no solder material reduces the insulation distance between the pads below the arrester.
- SMD surge arresters should be soldered within 24 month after shipment.

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Important notes

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